Advanced Power MOSFET

IRFS150A

FEATURES

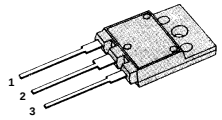
- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- 175℃ Operating Temperature
- Lower Leakage Current : 10 μA (Max.) @ V_{DS} = 100V
- Lower $R_{DS(ON)}$: 0.032 Ω(Typ.)

BV_{DSS} = 100 V

$R_{DS(on)}$ = 0.04 Ω

I_D = 31 A

TO-3PF



1.Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	100	V
I_D	Continuous Drain Current (T_C=25℃)	31	A
	Continuous Drain Current (T_C=100℃)	21.9	
I_{DM}	Drain Current-Pulsed ①	170	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy ②	641	mJ
I_{AR}	Avalanche Current ①	31	A
E_{AR}	Repetitive Avalanche Energy ①	10	mJ
dv/dt	Peak Diode Recovery dv/dt ③	6.5	V/ns
P_D	Total Power Dissipation (T_C=25℃)	100	W
	Linear Derating Factor	0.67	W/℃
T_J , T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +175	℃
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	1.5	℃/W
$R_{\theta JA}$	Junction-to-Ambient	--	40	

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Electrical Characteristics (T_C=25℃ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	100	--	--	V	V_{GS}=0V,I_D=250μA
$\Delta BV/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.11	--	V/℃	I_D=250μA ***See Fig 7***
$V_{GS(th)}$	Gate Threshold Voltage	2.0	--	4.0	V	V_{DS}=5V,I_D=250μA
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	V_{GS}=20V
	Gate-Source Leakage , Reverse	--	--	-100		V_{GS}=-20V
I_{DSS}	Drain-to-Source Leakage Current	--	--	10	μA	V_{DS}=100V
		--	--	100		V_{DS}=80V,T_C=150℃
$R_{DS(on)}$	Static Drain-Source On-State Resistance	--	--	0.04	Ω	V_{GS}=10V,I_D=15.5A ④
g_{fs}	Forward Transconductance	--	27.3	--	Ω	V_{DS}=40V,I_D=15.5A ④
C_{iss}	Input Capacitance	--	1750	2270	pF	V_{GS}=0V,V_{DS}=25V,f =1MHz ***See Fig 5***
C_{oss}	Output Capacitance	--	420	485		
C_{rss}	Reverse Transfer Capacitance	--	185	215		
$t_{d(on)}$	Turn-On Delay Time	--	17	50	ns	V_{DD}=50V,I_D=40A, R_G=6.2Ω ***See Fig 13*** ④⑤
t_r	Rise Time	--	20	50		
$t_{d(off)}$	Turn-Off Delay Time	--	80	160		
t_f	Fall Time	--	45	100		
Q_g	Total Gate Charge	--	75	97	nC	V_{DS}=80V,V_{GS}=10V, I_D=40A ***See Fig 6 & Fig 12*** ④⑤
Q_{gs}	Gate-Source Charge	--	13.2	--		
Q_{gd}	Gate-Drain(“Miller”) Charge	--	34.8	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_S	Continuous Source Current	--	--	31	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	170		
V_{SD}	Diode Forward Voltage ④	--	--	1.6	V	T_J=25℃,I_S=31A,V_{GS}=0V
t_{rr}	Reverse Recovery Time	--	135	--	ns	T_J=25℃,I_F=40A di$_F$/dt=100A/μs ④
Q_{rr}	Reverse Recovery Charge	--	0.65	--	μC	

Notes ;

① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

② L=1mH, I_{AS}=31A, V_{DD}=25V, R_G=27Ω, Starting T_J=25°C

③ I_{SD} ≤ 40A, di/dt ≤ 470A/μs, V_{DD}≤ BV_{DSS}, Starting T_J=25°C

④ Pulse Test : Pulse Width = 250 μs, Duty Cycle ≤2%

⑤ Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

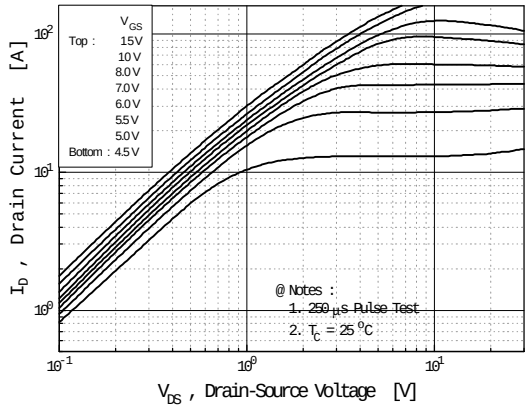


Fig 2. Transfer Characteristics

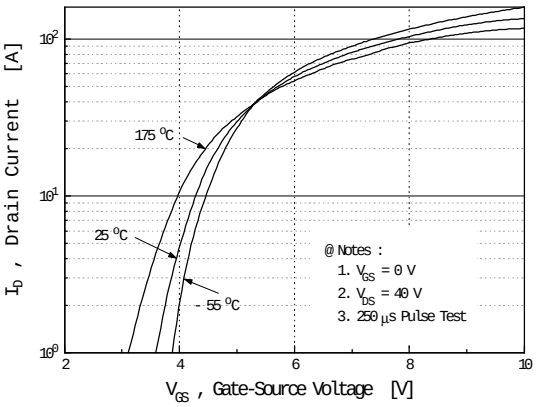


Fig 3. On-Resistance vs. Drain Current

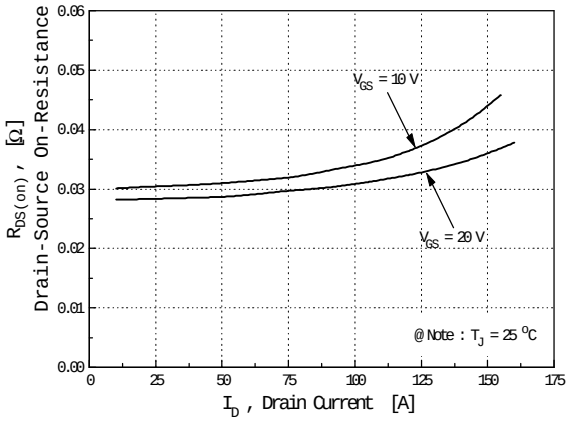


Fig 4. Source-Drain Diode Forward Voltage

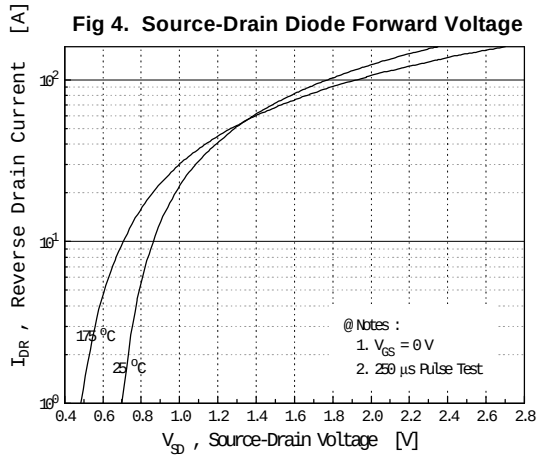


Fig 5. Capacitance vs. Drain-Source Voltage

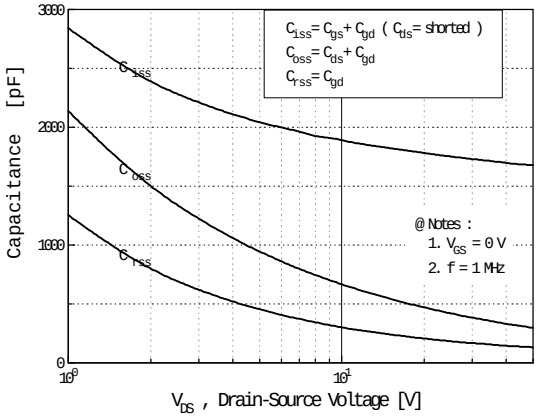


Fig 6. Gate Charge vs. Gate-Source Voltage

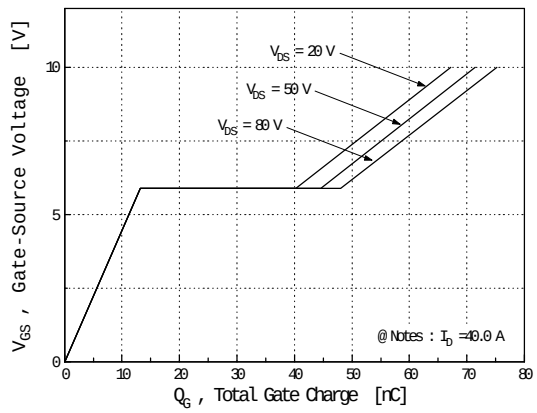


Fig 7. Breakdown Voltage vs. Temperature

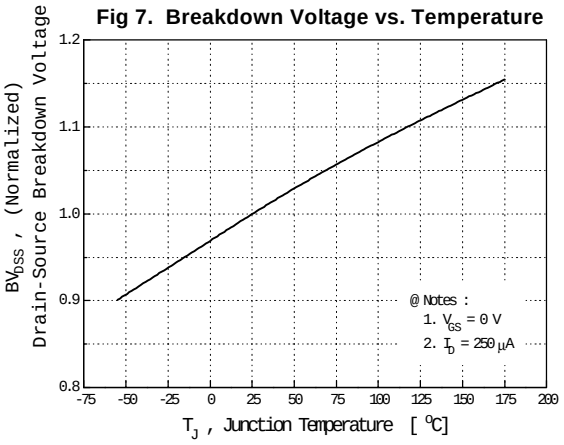


Fig 8. On-Resistance vs. Temperature

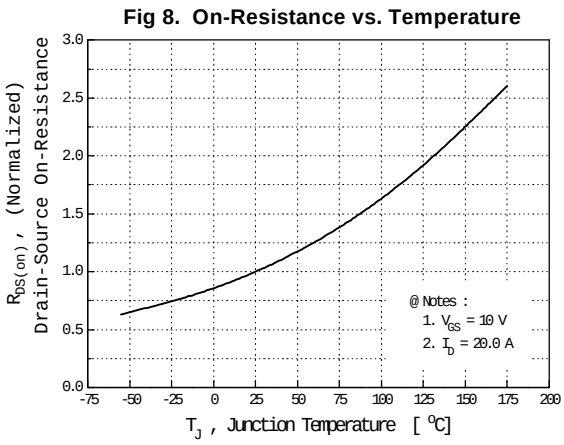


Fig 9. Max. Safe Operating Area

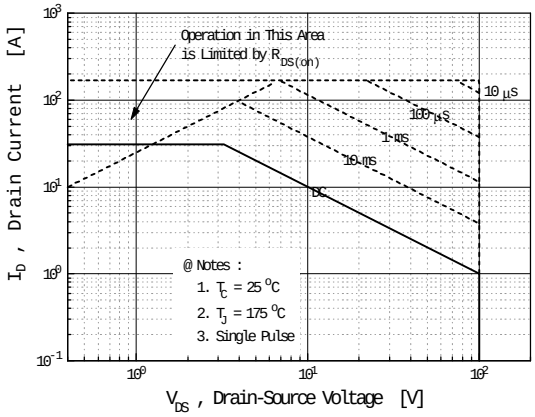


Fig 10. Max. Drain Current vs. Case Temperature

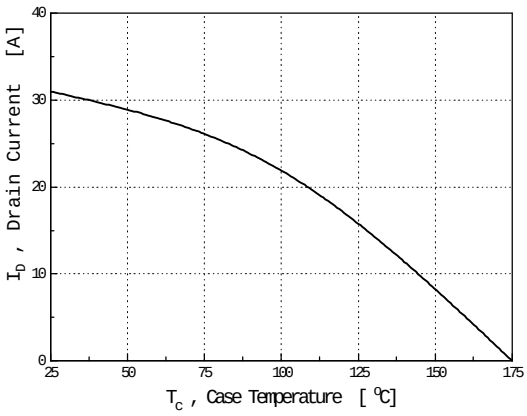


Fig 11. Thermal Response

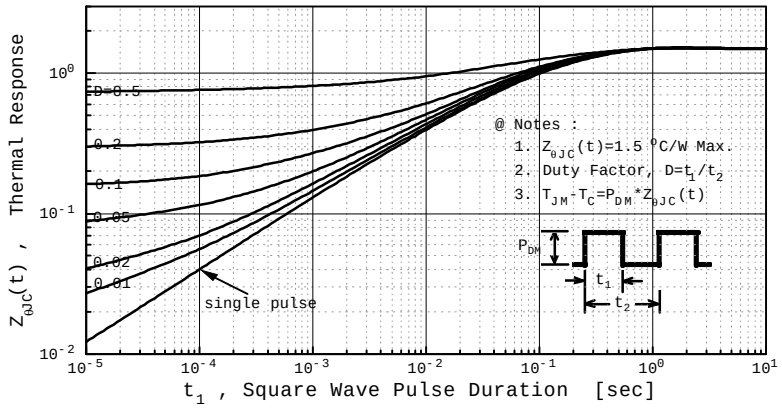


Fig 12. Gate Charge Test Circuit & Waveform

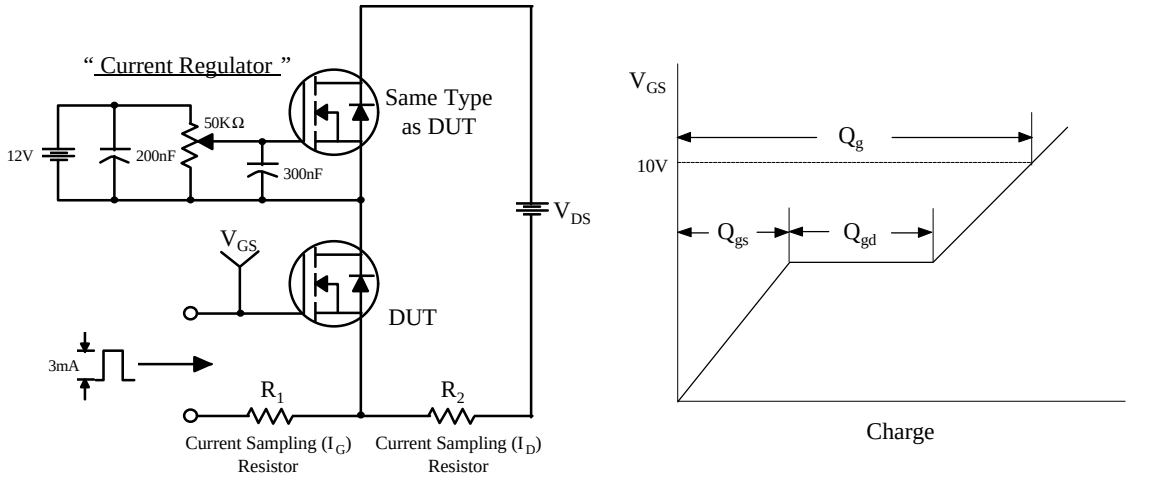


Fig 13. Resistive Switching Test Circuit & Waveforms

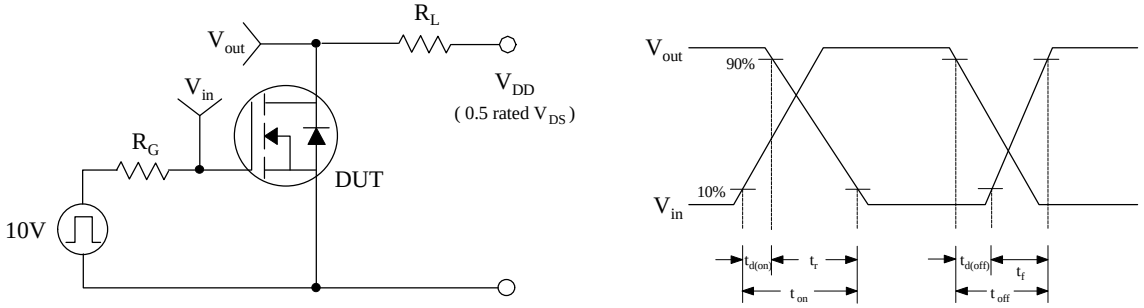


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

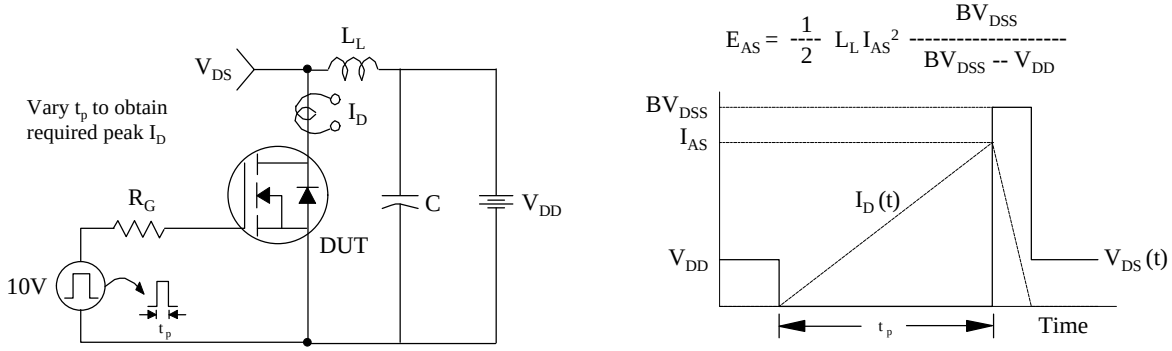
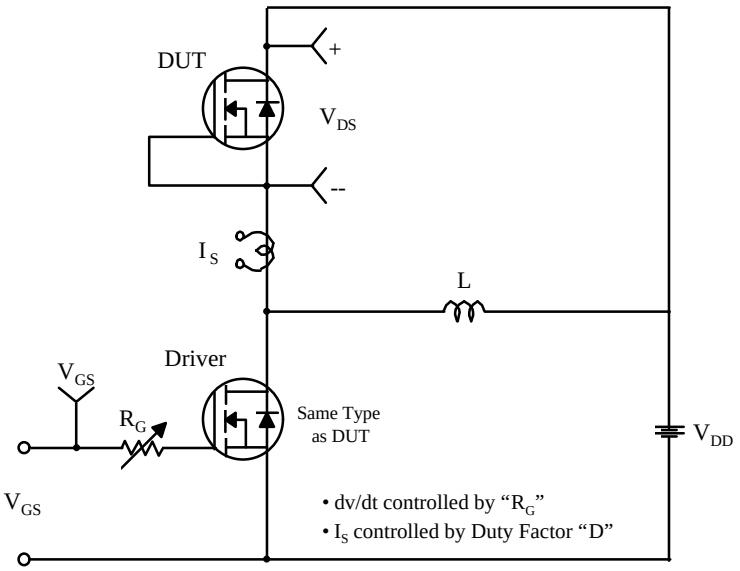
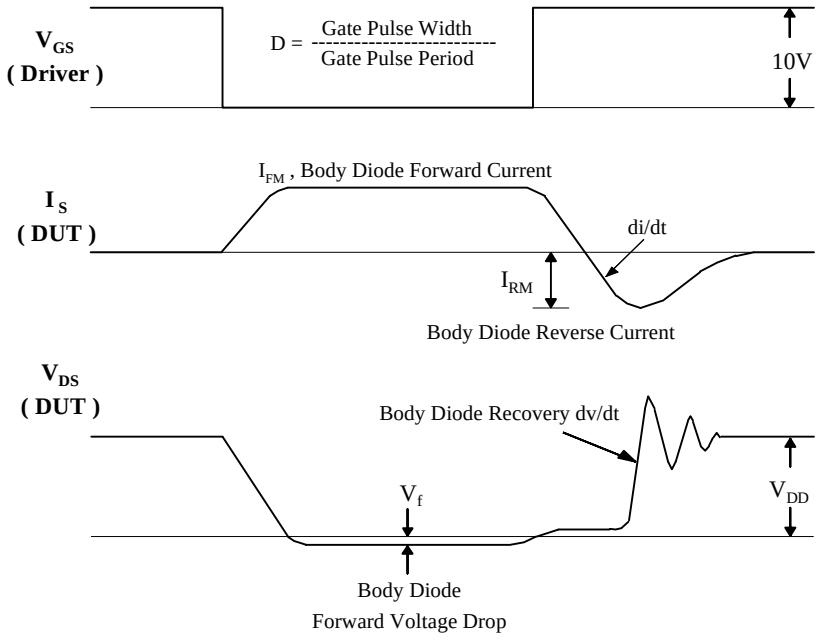


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





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